Product Qualification Report

BCR400W

Active Bias Controllers for RF Transistor

Description

This product qualification report describes the characteristics of the product with respect to quality and reliability.

The qualification sample selection was done on production lots which were manufactured and tested on standard production processes and meet the defined requirements.

The qualification test results of those products as outlined in this document are based on **AEC Q101** for target applications and may reference existing qualification results of similar products. Such referencing is justified by the structural similarity of the products.

Qualification Assessment

Qualified acc. **AEC Q101** and assessed as PASS

For further information about comparable products, please contact the nearest Infineon Technologies office (www.infineon.com).

BCR400W
PG-SOT343-4
MSL: 1, 260°C

qualified in 2005

Electrical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/ss	Fail/Qty	Result
Electrical Distribution	ED	-55°C, +25°C, +150°C		1 x 60	0 / 60	PASS
High Humidity High Temperature Reverse Bias JESD22 A101	H3TRB	Ta=85°C, RH=85%	1000 h	6 x 40	0 / 240	PASS
High Temperature Reverse Bias JESD22 A108	HTRB	Ta=150°C	1000 h	6 x 40	0 / 240	PASS
ESD Human Body Model JESD22 A114	HBM	Class 1B 500 to < 1000V		1 x 9	0 / 9	PASS
ESD Machine Model JESD22 A115	MM	Class A < 200V		1 x 12	0 / 12	PASS

Environmental Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Preconditioning J-STD020 / JESD22 A113	PC	Soak acc.MSL1, 3x reflow, 260°C		18 x 60	0 / 1080	PASS
Temperature Cycling* JESD22 A104	TC*	-55°C to +150°C	1000 cyc	12 x 60	0 / 720	PASS
Autoclave* JESD22 A102	AC*	Ta=121°C, RH=100%	96 h	6 x 60	0 / 360	PASS

Mechanical Stress Test Results:

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Destructive Physical Analysis	DPA	Random samples from H3TRB & TC		6 x 4	0 / 24	PASS
Physical Dimensions JESD B-100	PD			1 x 30	0 / 30	PASS
Resistance to Solder Heat JESD B-106	RTSH	Solder bath Ts=260°C, dip 3 x 10 sec		1 x 30	0 / 30	PASS
Solderability J-STD-002	SD			1 x 10	0 / 10	PASS

Notes:

* For SMD devices reliability stress tests performed after pre-conditioning test (PC)

Further abbreviations: MSL - moisture sensitivity level, Qty – quantity, RH – relative humidity, SS – sample size, Ta – ambient temperature, Ts – solder temperature

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Document reference

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